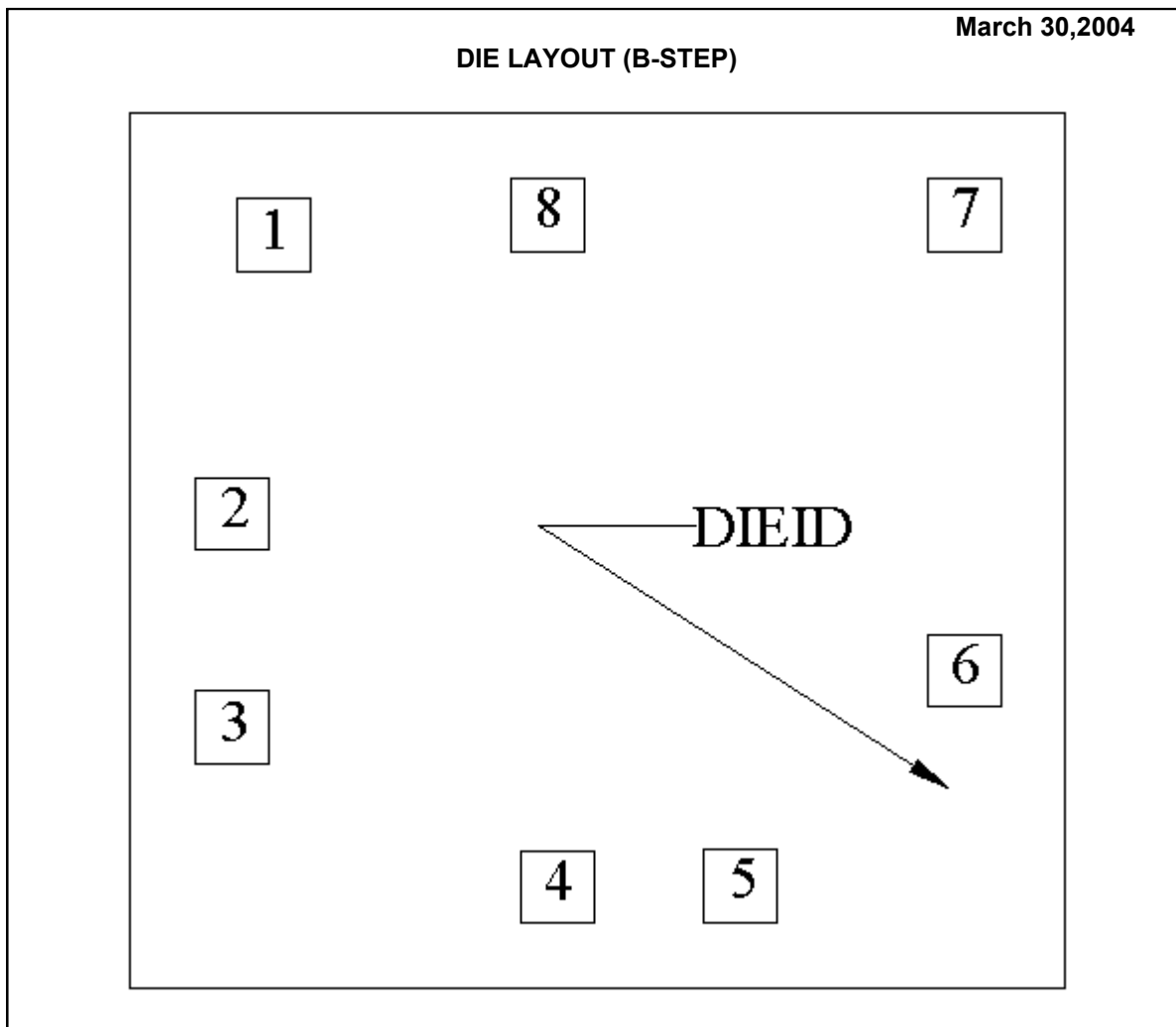


LM392 MDA MWA
LOW POWER OPERATIONAL AMPLIFIER/VOLTAGE COMPARATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	1924B	Bond Pad Opening Size (min)	91µm x 89µm
Die Step	B	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM_DLM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1092µm x 1168µm 43.0mils x 46.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	228µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT A (COMP)	1	-406	394	91	x	91
INPUT A -	2	-457	46	91	x	91
INPUT A+	3	-457	-221	91	x	91
GND	4	-51	-420	91	x	89
INPUT B+	5	178	-419	91	x	91
INPUT B -	6	457	-151	91	x	89
OUTPUT B (OP AMP)	7	457	419	91	x	91
V+	8	-64	419	91	x	91

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IN U.S.A.

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Fax: 1 207 541 6140

IN EUROPE

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